



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Anthony L. Coyle, et al.**

Docket No.: **TI-31794**

Serial No.: **09/992,387**

Examiner: **Lewis, M.**

Filed: **11/16/2001**

Art Unit.: **2822**

For: **Flip-Chip On Film Assembly For Ball Grid Array
Packages**

Conf. No.: **7595**

TRANSMITTAL OF FORMAL DRAWINGS

November 6, 2002

Assistant Commissioner For Patents
Attn: Official Drafts Person
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner For Patents, Washington, DC 20231.

Elizabeth Austin
Elizabeth Austin

11/6/2002
Date

Dear Sir:

Submitted herewith are 3 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Respectfully submitted,

Michael K. Skrehot

Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682

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